1.4MHz, Rail-to-Rail I/O CMOS Operational Amplifier

1 FEATURES

- **HIGH GAIN BANDWIDTH:1.4MHz**
- **RAIL-TO-RAIL INPUT AND OUTPUT ±0.1mV Typical Vos**
- **INPUT VOLTAGE RANGE: -0.1V to +5.6V with Vs = 5.5V**
- **SUPPLY RANGE: +2.2V to +5.5V**
- **SPECIFIED UP TO +125°C**
- **Micro SIZE PACKAGES: SOT23-5, SOP8, MSOP8, SOP14**

2 APPLICATIONS

- **SENSORS**
- **PHOTODIODE AMPLIFICATION**
- **ACTIVE FILTERS**
- **TEST EQUIPMENT**
- **DRIVING A/D CONVERTERS**

3 DESCRIPTIONS

The RS6331E, RS6332E, RS6334E families of products offer low voltage operation and rail-to-rail input and output, as well as excellent speed/power consumption ratio, providing an excellent bandwidth (1.4MHz) and slew rate of 0.5V/μs. The op-amps are unity gain stable and feature an ultra-low input bias current.

The devices are ideal for sensor interfaces, active filters, and portable applications. The RS6331E, RS6332E, RS6334E families of operational amplifiers are specified at the full temperature range of -40°C to +125°C under single or dual power supplies of 2.2V to 5.5V.

Device Information [1]

PART NUMBER	PACKAGE	BODY SIZE(NOM)
RS6331E	SOT23-5	2.90mm×1.60mm
RS6332E	SOP8	4.90mm×3.90mm
	MSOP8	3.00mm×3.00mm
RS6334E	SOP14	8.65mm×3.90mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Table of Contents

4 REVISION HISTORY

Note: Page numbers for previous revisions may different from page numbers in the current version.

| Version	Change Date	Change Item
A.1	2024/03/12	Initial version completed
A.2	2025/04/25	1. Delete SC70-5/TSSOP8/TSSOP14 Package 2. Update ELECTRICAL CHARACTERISTICS

5 PACKAGE/ORDERING INFORMATION [1]

Orderable Device	Package Type	Pin	Channel	Op Temp(°C)	Device Marking [2]	MSL[3]	Package Qty
RS6331EXF	SOT23-5	5	1	-40°C ~125°C	6331E	MSL3	Tape and Reel,3000
RS6331BEXF	SOT23-5	5	1	-40°C ~125°C	6331BE	MSL3	Tape and Reel,3000
RS6332EXK	SOP8	8	2	-40°C ~125°C	RS6332E	MSL3	Tape and Reel,4000
RS6332EXM	MSOP8	8	2	-40°C ~125°C	RS6332E	MSL3	Tape and Reel,4000
RS6334EXP	SOP14	14	4	-40°C ~125°C	RS6334E	MSL3	Tape and Reel,4000

NOTE:
(1) This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the right-hand navigation.
(2) There may be additional marking, which relates to the lot trace code information (data code and vendor code), the logo or the environmental category on the device.
(3) RUNIC classify the MSL level with using the common preconditioning setting in our assembly factory conforming to the JEDEC industrial standard J-STD-20F, Please align with RUNIC if your end application is quite critical to the preconditioning setting or if you have special requirement.
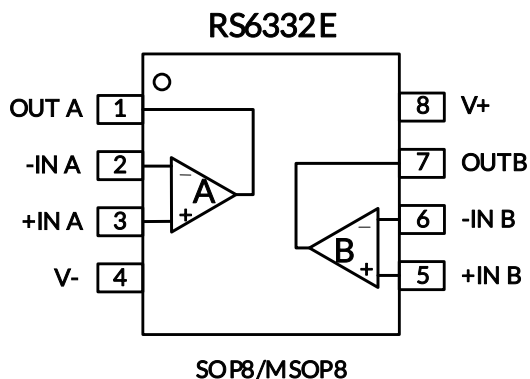
6 PIN CONFIGURATION AND FUNCTIONS (TOP VIEW)

RS6331E

RS6331BE
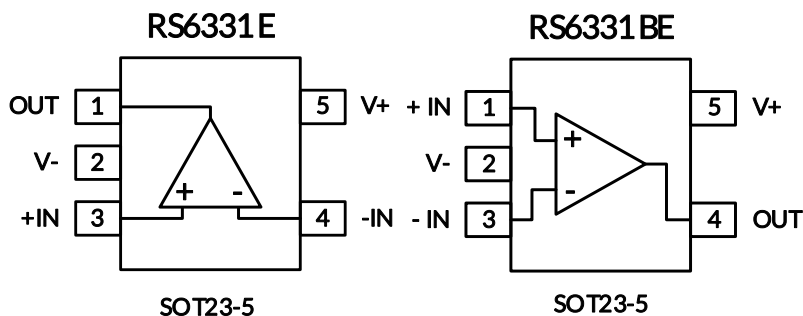
SOT23-5

SOT23-5

Pin Description

NAME	PIN		I/O [1]	DESCRIPTION
	RS6331E	**RS6331BE**		
	SOT23-5	**SOT23-5**		
-IN	4	3	I	Negative (inverting) input
+IN	3	1	I	Positive (noninverting) input
OUT	1	4	O	Output
V-	2	2	-	Negative (lowest) power supply
V+	5	5	-	Positive (highest) power supply

(1)   I = Input, O = Output.

RS6332E

SOP8/MSOP8

Pin Description

NAME	PIN	I/O [1]	DESCRIPTION
	SOP8/MSOP8		
-INA	2	I	Inverting input, channel A
+INA	3	I	Noninverting input, channel A
-INB	6	I	Inverting input, channel B
+INB	5	I	Noninverting input, channel B
OUTA	1	O	Output, channel A
OUTB	7	O	Output, channel B
V-	4	-	Negative (lowest) power supply
V+	8	-	Positive (highest) power supply

(1)   I = Input, O = Output.

PIN CONFIGURATION AND FUNCTIONS (TOP VIEW)
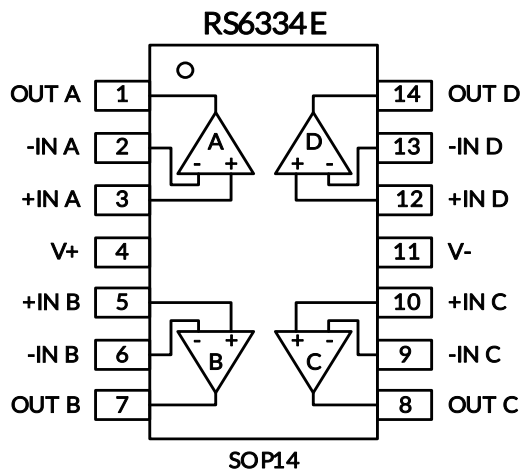
RS6334E

OUT A	1		14	OUT D
-IN A	2	A	13	-IN D
+IN A	3		12	+IN D
V+	4		11	V-
+IN B	5		10	+IN C
-IN B	6	B	9	-IN C
OUT B	7		8	OUT C

SOP14

Pin Description

NAME	PIN SOP14	I/O (1)	DESCRIPTION
-INA	2	I	Inverting input, channel A
+INA	3	I	Noninverting input, channel A
-INB	6	I	Inverting input, channel B
+INB	5	I	Noninverting input, channel B
-INC	9	I	Inverting input, channel C
+INC	10	I	Noninverting input, channel C
-IND	13	I	Inverting input, channel D
+IND	12	I	Noninverting input, channel D
OUTA	1	O	Output, channel A
OUTB	7	O	Output, channel B
OUTC	8	O	Output, channel C
OUTD	14	O	Output, channel D
V-	11	-	Negative (lowest) power supply
V+	4	-	Positive (highest) power supply

(1)   I = Input, O = Output.

7 SPECIFICATIONS

7.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted) [1]

			MIN	MAX	UNIT
Voltage	Supply, V_S=(V+) - (V-)			7	V
	Signal input pin [2]		(V-)-0.5	(V+) +0.5	
	Signal output pin [3]		(V-)-0.5	(V+) +0.5	
Current	Signal input pin [2]		-10	10	mA
	Signal output pin [3]		-150	150	mA
	Output short-circuits [4]		Continuous		
θ_{JA}	Package thermal impedance [5]	SOT23-5		230	°C/W
		SOP8		110.88	
		MSOP8		165.7	
		SOP14		104.5	
Temperature	Operating range, T_A		-40	125	°C
	Junction, T_J [6]		-40	150	
	Storage, T_{stg}		-65	150	

(1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.
(2) Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.5V beyond the supply rails should be current-limited to 10mA or less.
(3) Output terminals are diode-clamped to the power-supply rails. Output signals that can swing more than 0.5V beyond the supply rails should be current-limited to ±150mA or less.
(4) Short-circuit to ground, one amplifier per package.
(5) The package thermal impedance is calculated in accordance with JESD-51.
(6) The maximum power dissipation is a function of $T_{J(MAX)}$, $R_{\theta JA}$, and T_A. The maximum allowable power dissipation at any ambient temperature is $P_D = (T_{J(MAX)} - T_A) / R_{\theta JA}$. All numbers apply for packages soldered directly onto a PCB.

7.2 ESD Ratings

The following ESD information is provided for handling of ESD-sensitive devices in an ESD protected area only.

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001[1]	±5000	V
		Charged-device model (CDM), per ANSI/ESDA/JEDEC JS-002[2]	±1000	
		Machine Model (MM)	±400	

(1) JEDEC document JEP155 states that 500 V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250 V CDM allows safe manufacturing with a standard ESD control process.

ESD SENSITIVITY CAUTION

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

7.3 Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
Supply voltage, V_S= (V+) - (V-)	Single-supply	2.2		5.5	V
	Dual-supply	±1.1		±2.75	

7.4 ELECTRICAL CHARACTERISTICS

(At T_A = +25°C, V_S=2.2V to 5.5V, R_L = 10kΩ connected to V_S/2, and V_{OUT} = V_S/2, V_{CM} = V_S/2, Full [9] = -40°C to +125°C, unless otherwise noted.) [1]

PARAMETER		CONDITIONS	T_J	RS6331E, RS6332E, RS6334E			UNIT
				MIN[2]	TYP[3]	MAX[2]	
POWER SUPPLY							
V_S	Operating Voltage Range		25°C	2.2		5.5	V
I_Q	Quiescent Current Per Amplifier	V_S=±2.5V, Io=0mA	25°C		62.5	85	µA
PSRR	Power-Supply Rejection Ratio	V_S=2.2V to 5.5V	25°C	75	92		dB
			Full	65			
INPUT							
V_{OS}	Input Offset Voltage	V_{CM}= V_S/2, RS6332E	25°C	-0.8	±0.1	0.8	mV
		V_{CM}= V_S/2, RS6331E/ RS6334E	25°C	-1	±0.1	1	
V_{OS} T_C	Input Offset Voltage Average Drift	V_{CM}= V_S/2	Full		±1		µV/°C
IB	Input Bias Current [4] [5]	V_{CM}=0V	25°C		±1	±10	pA
Ios	Input Offset Current [5]	V_{CM}=0V	25°C		±1	±10	pA
V_{CM}	Common-Mode Voltage Range	V_S= 5.5V	25°C	-0.1		5.6	V
CMRR	Common-Mode Rejection Ratio	V_S= 5.5V V_{CM}=-0.1V to 3.5V	25°C	74	93		dB
			Full	63			
		V_S= 5.5V V_{CM}=-0.1V to 5.6V	25°C	60	77		
			Full	59			
OUTPUT							
A_{OL}	Open-Loop Voltage Gain	R_L=10KΩ,Vo=(V-)+0.1V to (V+)-0.1V	25°C	110	122		dB
			Full	87			
	Output Swing From Rail	V_S= ±2.5V, R_L=10KΩ	25°C		10	20	mV
I_{OUT}	Output Short-Circuit Current[6] [7]		25°C	±60	±96		mA
C_{LOAD}	Capacitive Load Drive				100		pF
FREQUENCY RESPONSE							
SR	Slew Rate [8]	G=+1, C_L=100pF	25°C		0.5		V/µs
GBP	Gain-Bandwidth Product		25°C		1.4		MHz
PM	Phase Margin [5]		25°C		64		°
t_S	Settling Time,0.1%	V_S=±2.5V, G=+1, C_L=100pF, Step=2V	25°C		6.5		µs
t_{OR}	Overload Recovery Time	V_{IN}·Gain≥V_S,G=-10	25°C		5.3		µs
NOISE							
E_n	Input Voltage Noise	f = 0.1Hz to 10Hz, V_S=±2.5V	25°C		4.5		µV$_{PP}$
e_n	Input Voltage Noise Density	f = 1KHz	25°C		47		nV/$\sqrt{Hz}$

NOTE:

(1) Electrical table values apply only for factory testing conditions at the temperature indicated. Factory testing conditions result in very limited self-heating of the device.

(2) Limits are 100% production tested at 25°C. Limits over the operating temperature range are ensured through correlations using statistical quality control (SQC) method.

(3) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.

(4) Positive current corresponds to current flowing into the device.

(5) This parameter is ensured by design and/or characterization and is not tested in production.

(6) The maximum power dissipation is a function of $T_{J(MAX)}$, $R_{\theta JA}$, and T_A. The maximum allowable power dissipation at any ambient temperature is PD = ($T_{J(MAX)}$ - T_A) / $R_{\theta JA}$. All numbers apply for packages soldered directly onto a PCB.

(7) Short circuit test is a momentary test.

(8) Number specified is the slower of positive and negative slew rates.

(9) Specified by characterization only.

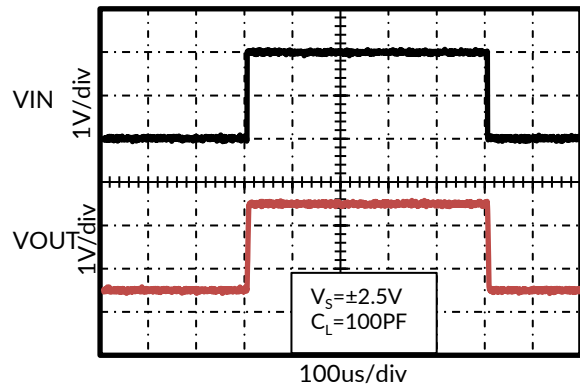## 7.5 TYPICAL CHARACTERISTICS

NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.

At T_A = +25°C, Vs=5V, R_L = 10kΩ connected to V_S/2, V_{OUT} = V_S/2, unless otherwise noted.
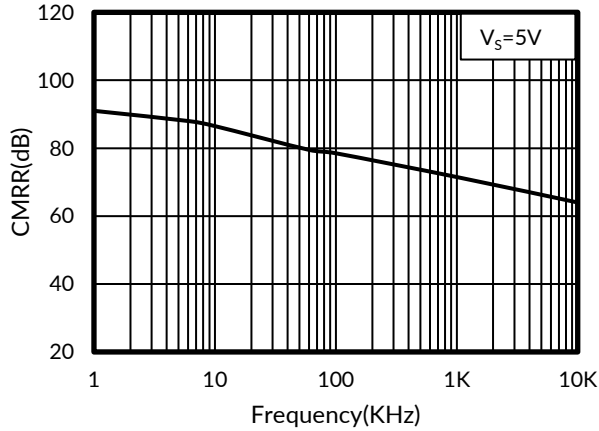
Figure 1. Common−mode Rejection Ratio vs Frequency
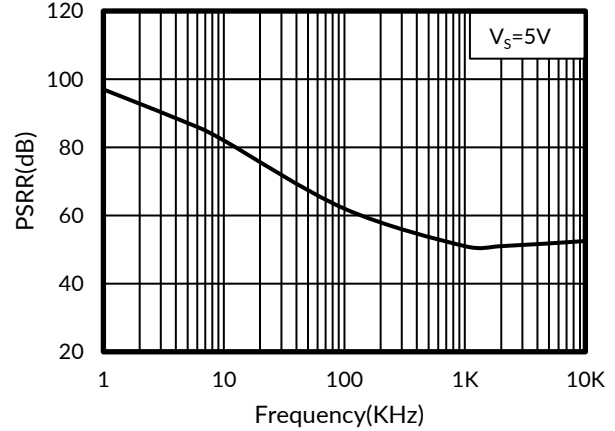
Figure 2. Power-Supply Rejection Ratio vs Frequency
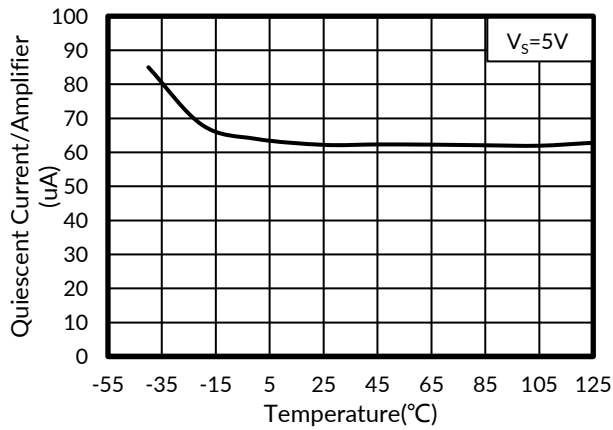
Figure 3. Quiescent Current vs Temperature
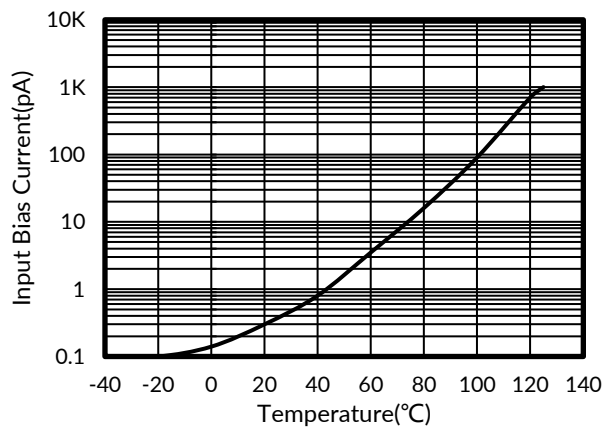
Figure 4. Input Bias Current vs Temperature
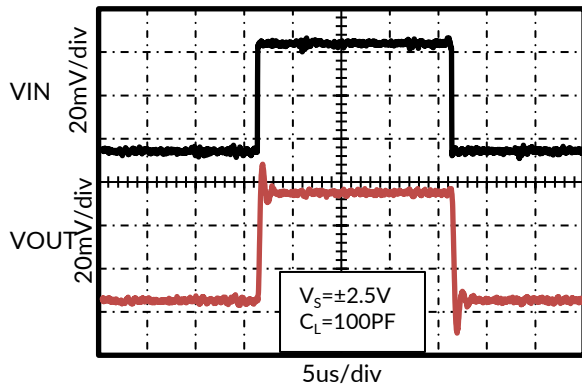
Figure 5. Small-Signal Step Response

Figure 6. Large-Signal Step Response

TYPICAL CHARACTERISTICS

NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.

At T_A = +25°C, Vs=5V, R_L = 10kΩ connected to V_S/2, V_{OUT} = V_S/2, unless otherwise noted.
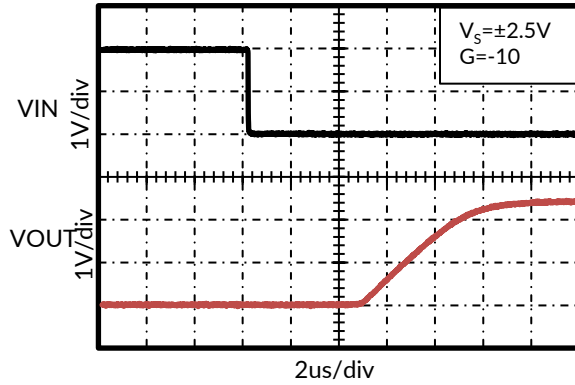
Figure 7. Negative Overvoltage Recovery
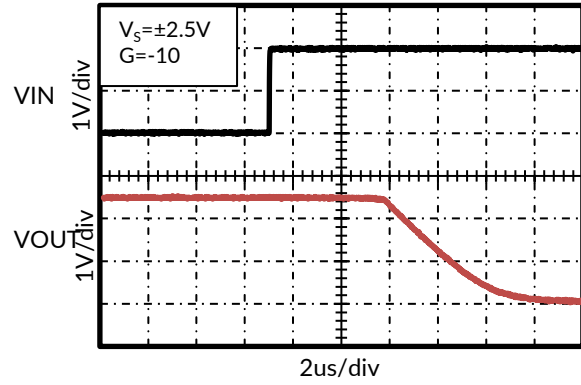
Figure 8. Positive Overvoltage Recovery
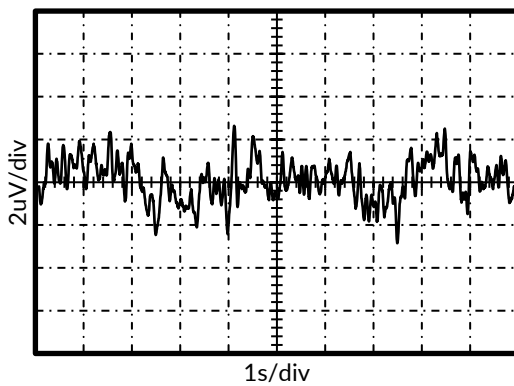
Figure 9. 0.1Hz to 10Hz Input Voltage Noise

8 APPLICATION AND IMPLEMENTATION

Information in the following applications sections is not part of the RUNIC component specification, and RUNIC does not warrant its accuracy or completeness. RUNIC's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 APPLICATION NOTES

The RS6331E, RS6332E, RS6334E are high precision, rail-to-rail operational amplifiers that can be run from a single-supply voltage 2.2V to 5.5V (±1.1V to ±2.75V). Supply voltages higher than 7V (absolute maximum) can permanently damage the amplifier. Rail-to-rail input and output swing significantly increases dynamic range, especially in low-supply applications. Good layout practice mandates use of a 0.1uF capacitor place closely across the supply pins.

8.2 LAYOUT GUIDELINS

Attention to good layout practices is always recommended. Keep traces short. When possible, use a PCB ground plane with surface-mount components placed as close to the device pins as possible. Place a 0.1uF capacitor closely across the supply pins. These guidelines should be applied throughout the analog circuit to improve performance and provide benefits such as reducing the EMI susceptibility.
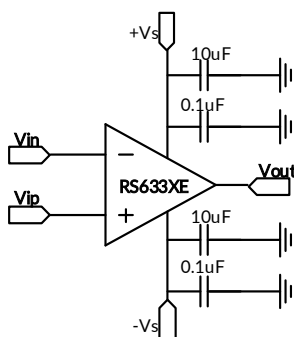

Figure 10. Amplifier with Bypass Capacitors

8.3 INSTRUMENTATION AMPLIFIER

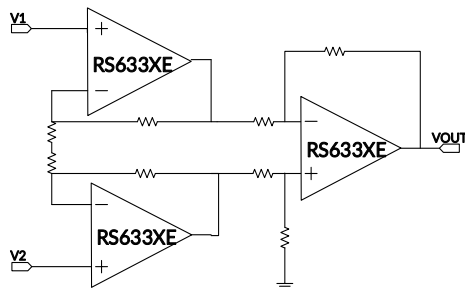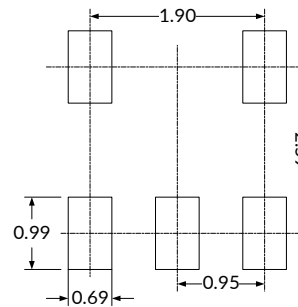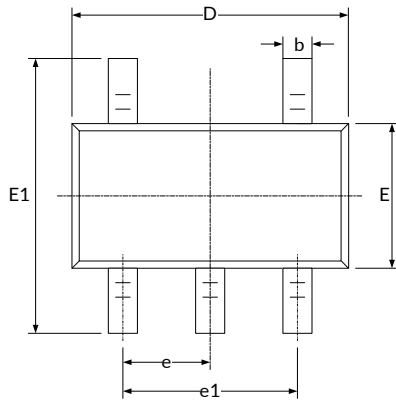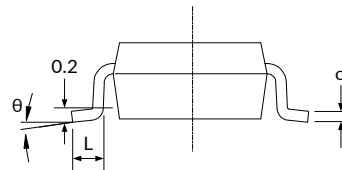In the three-op amp, instrumentation amplifier configuration shown in Figure 11.
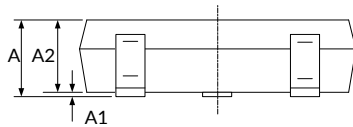

Figure 11. Amplifier instrumentation amplifier

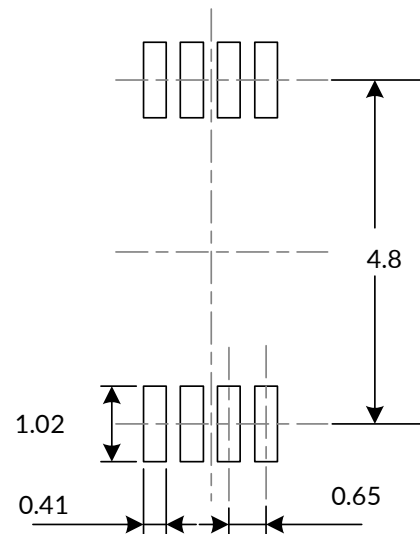# 9 PACKAGE OUTLINE DIMENSIONS
SOT23-5 [3]

RECOMMENDED LAND PATTERN (Unit: mm)

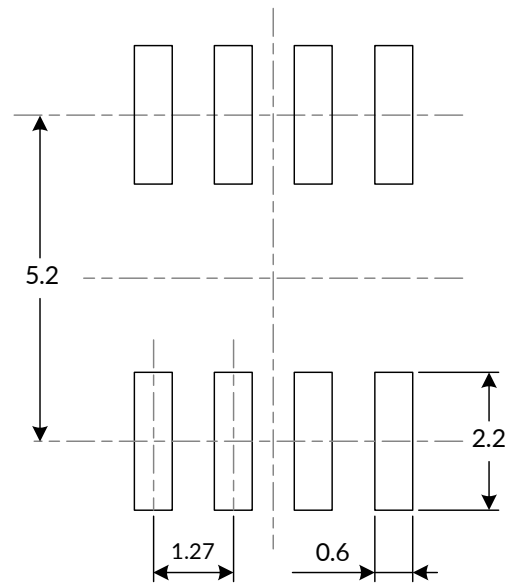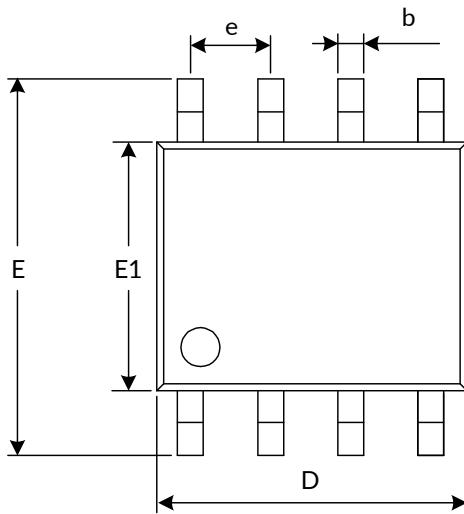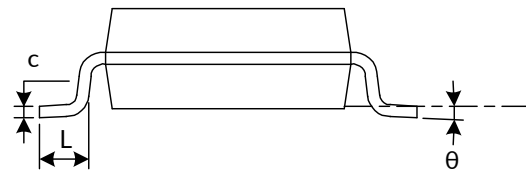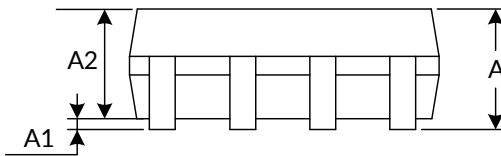| Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A [1]	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D [1]	2.820	3.020	0.111	0.119
E [1]	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC) [2]		0.037(BSC) [2]	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

NOTE:
1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.

MSOP8 [3]
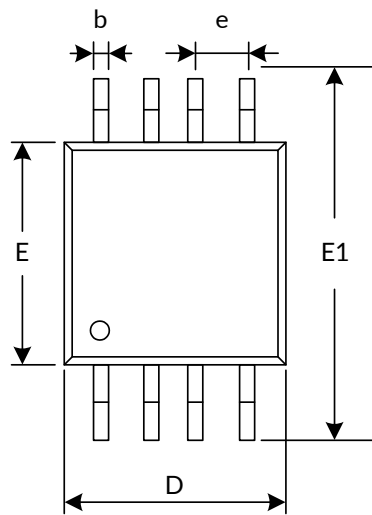
RECOMMENDED LAND PATTERN (Unit: mm)
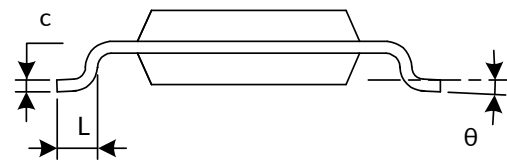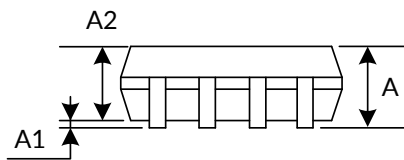
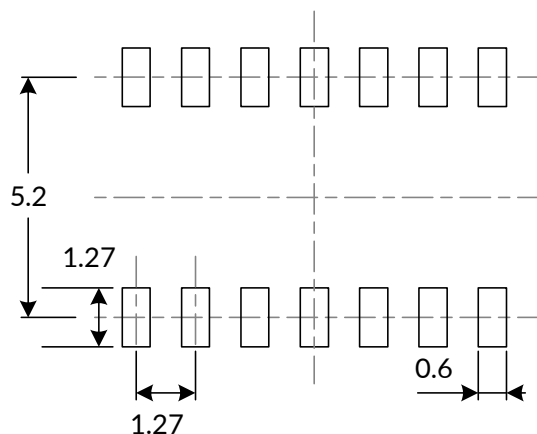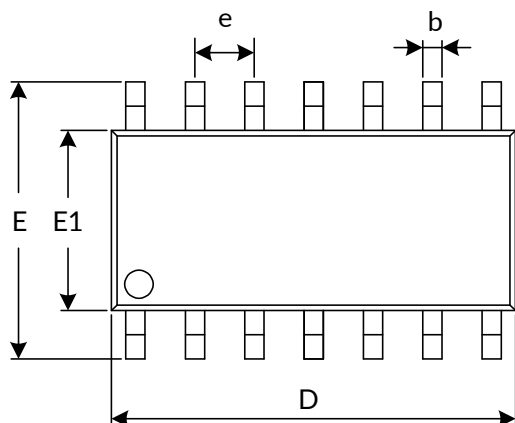| Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A [1]	0.820	1.100	0.032	0.043
A1	0.020	0.150	0.001	0.006
A2	0.750	0.950	0.030	0.037
b	0.250	0.380	0.010	0.015
c	0.090	0.230	0.004	0.009
D [1]	2.900	3.100	0.114	0.122
e	0.650(BSC) [2]		0.026(BSC) [2]	
E [1]	2.900	3.100	0.114	0.122
E1	4.750	5.050	0.187	0.199
L	0.400	0.800	0.016	0.031
θ	0°	6°	0°	6°

NOTE:
1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.

SOP8 (3)

RECOMMENDED LAND PATTERN (Unit: mm)

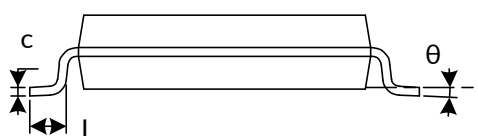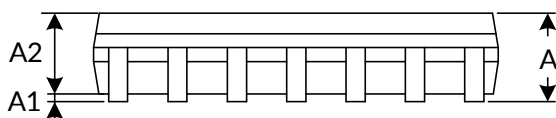| Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A (1)	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D (1)	4.800	5.000	0.189	0.197
e	1.270(BSC) (2)		0.050(BSC) (2)	
E	5.800	6.200	0.228	0.244
E1 (1)	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

NOTE:
1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.

SOP14 [3]

RECOMMENDED LAND PATTERN (Unit: mm)

| Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A [1]	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.310	0.510	0.012	0.020
c	0.100	0.250	0.004	0.010
D [1]	8.450	8.850	0.333	0.348
e	1.270(BSC) [2]		0.050(BSC) [2]	
E	5.800	6.200	0.228	0.244
E1 [1]	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

NOTE:
1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.

10 TAPE AND REEL INFORMATION

REEL DIMENSIONS
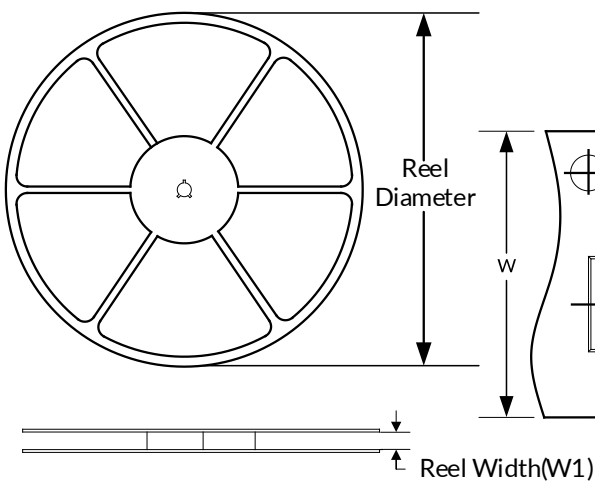
TAPE DIMENSION
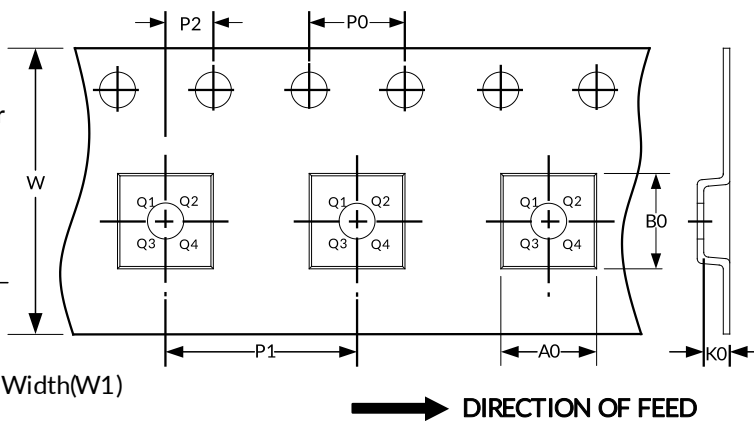
NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
SOT23-5	7"	9.5	3.20	3.20	1.40	4.0	4.0	2.0	8.0	Q3
MSOP8	13"	12.4	5.20	3.30	1.50	4.0	8.0	2.0	12.0	Q1
SOP8	13"	12.4	6.40	5.40	2.10	4.0	8.0	2.0	12.0	Q1
SOP14	13"	16.4	6.60	9.30	2.10	4.0	8.0	2.0	16.0	Q1

NOTE:
1. All dimensions are nominal.
2. Plastic or metal protrusions of 0.15mm maximum per side are not included.

IMPORTANT NOTICE AND DISCLAIMER

Jiangsu RUNIC Technology Co., Ltd. will accurately and reliably provide technical and reliability data (including data sheets), design resources (including reference designs), application or other design advice, WEB tools, safety information and other resources, without warranty of any defect, and will not make any express or implied warranty, including but not limited to the warranty of merchantability Implied warranty that it is suitable for a specific purpose or does not infringe the intellectual property rights of any third party.

These resources are intended for skilled developers designing with RUNIC products You will be solely responsible for: (1) Selecting the appropriate products for your application; (2) Designing, validating and testing your application; (3) Ensuring your application meets applicable standards and any other safety, security or other requirements; (4) RUNIC and the RUNIC logo are registered trademarks of RUNIC INCORPORATED. All trademarks are the property of their respective owners; (5) For change details, review the revision history included in any revised document. The resources are subject to change without notice. Our company will not be liable for the use of this product and the infringement of patents or third-party intellectual property rights due to its use.